Multi-Chip Module With Stacked Dice

Abstract of the Disclosure

A multi-chip module may be formed by wire bonding a first chip within a cavity in a multi-chip carrier. A second die may be positioned over the first die, elevated therefrom, using bump bonding. In some embodiments, only a single cavity is utilized and in other embodiments, multiple cavities may be utilized, one of which mounts a first chip and the other of which mounts a second chip. In some embodiments, the second chip may be a composite of two dice coupled back-to-back so that the lowermost die may be bump bonded to the carrier and the uppermost die, facing upwardly away from the carrier, may be wire bonded thereto.

This Sheet Has Been Replaced

